



UV Curable Dicing Tape



- High adhesive strength
- Secures wafers firmly
- Easy removal after exposure.
- Small-die application
- Non-standard substrates
- FR4 board BGA wafers

Product	SEC P/N	Adhesion	Thickness	Applications
DU-2187G	25551	High Tack	88um	Backside Metalization
DU-300	24339	High Tack	85um	Thin Wafers, Silicon Die
NBD-3190K	25587	Super High Tack	193um	Glass Substrates
NBD-5170K	24351	Super High Tack	170um	Resin or Ceramic
NBD-7167K	25836	High Tack	160um	Resin or Ceramic
UE110-BJR	24591	High Tack	100um	Stealth
WS-02T	25862	Medium Tack	88um	

** Available in 230mm, 300mm, 330mm and 400mm widths

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